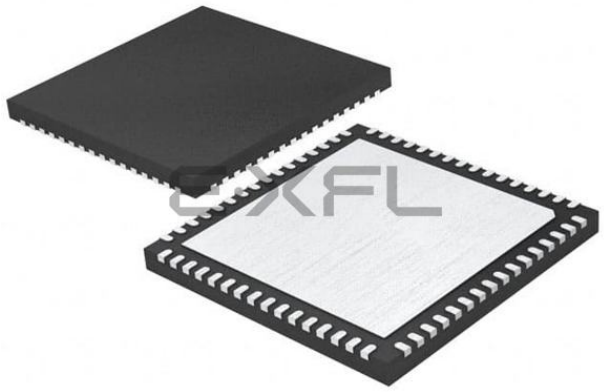
Microchip Technology - PIC24EP128MC206-I/MR Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

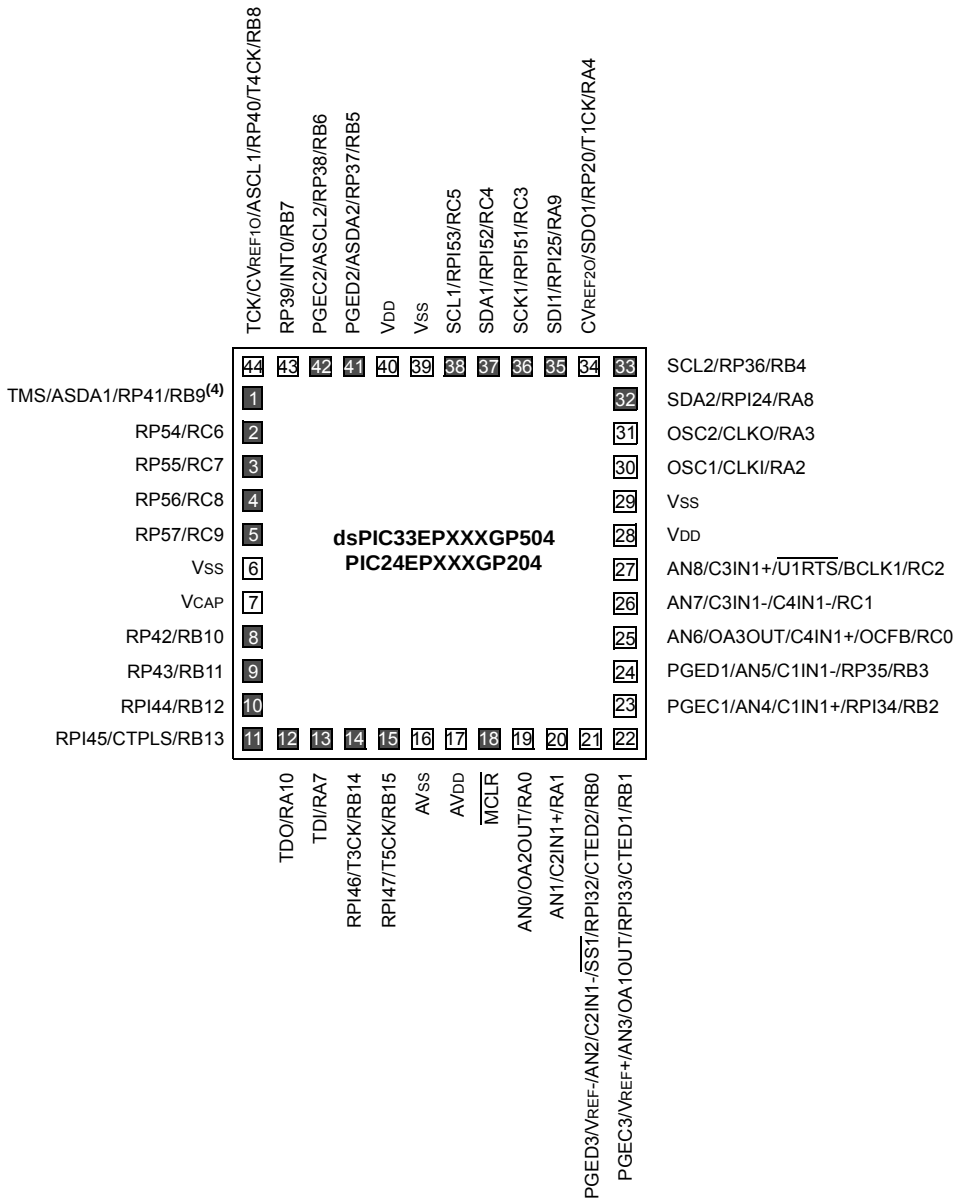
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	53
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep128mc206-i-mr

Pin Diagrams (Continued)

44-Pin VTLA(1,2,3)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

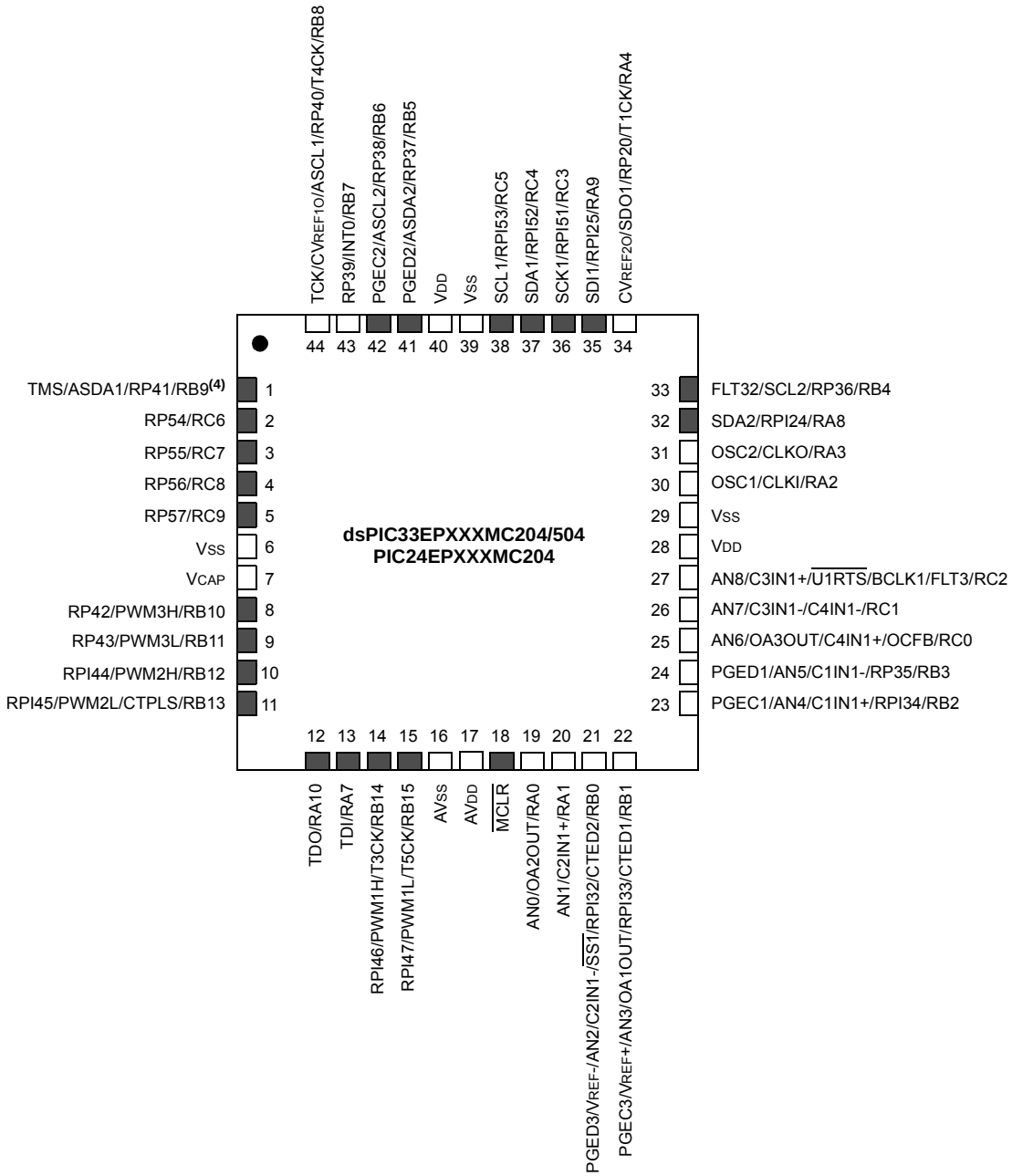
3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

Pin Diagrams (Continued)

44-Pin QFN(1,2,3)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

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3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

1.0 DEVICE OVERVIEW

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive resource. To complement the information in this data sheet, refer to the related section of the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com)

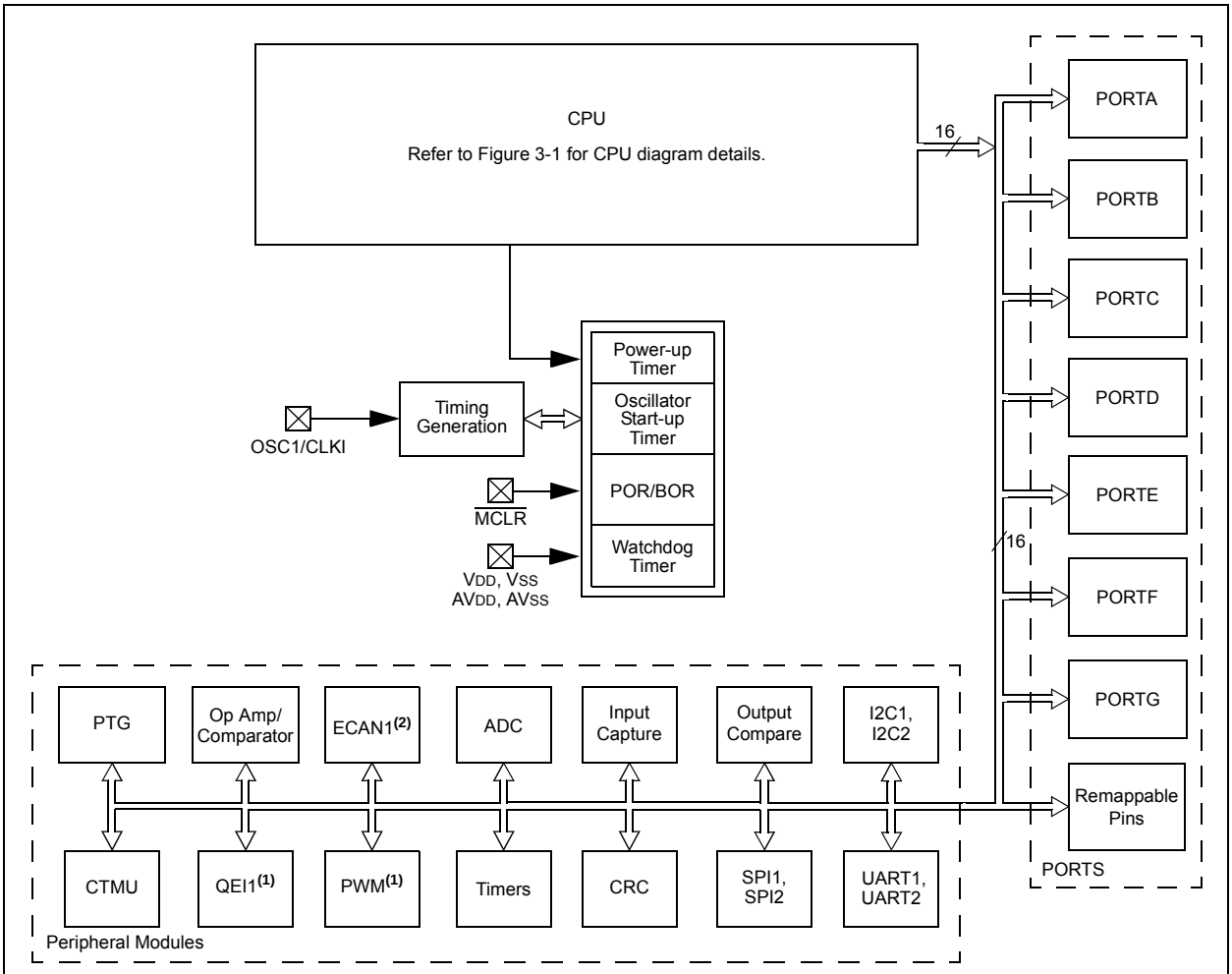
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

This document contains device-specific information for the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X Digital Signal Controller (DSC) and Microcontroller (MCU) devices.

dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices contain extensive Digital Signal Processor (DSP) functionality with a high-performance, 16-bit MCU architecture.

Figure 1-1 shows a general block diagram of the core and peripheral modules. Table 1-1 lists the functions of the various pins shown in the pinout diagrams.

FIGURE 1-1: dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X AND PIC24EPXXXGP/MC20X BLOCK DIAGRAM



Note 1: This feature or peripheral is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

2: This feature or peripheral is only available on dsPIC33EPXXXGP/MC50X devices.

3.7 CPU Control Registers

REGISTER 3-1: SR: CPU STATUS REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/C-0	R/C-0	R-0	R/W-0
OA(1)	OB(1)	SA(1,4)	SB(1,4)	OAB(1)	SAB(1)	DA(1)	DC
bit 15							bit 8

R/W-0(2,3)	R/W-0(2,3)	R/W-0(2,3)	R-0	R/W-0	R/W-0	R/W-0	R/W-0
IPL2	IPL1	IPL0	RA	N	OV	Z	C
bit 7							bit 0

Legend:	C = Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1'= Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **OA:** Accumulator A Overflow Status bit(1)
1 = Accumulator A has overflowed
0 = Accumulator A has not overflowed

bit 14 **OB:** Accumulator B Overflow Status bit(1)
1 = Accumulator B has overflowed
0 = Accumulator B has not overflowed

bit 13 **SA:** Accumulator A Saturation 'Sticky' Status bit(1,4)
1 = Accumulator A is saturated or has been saturated at some time
0 = Accumulator A is not saturated

bit 12 **SB:** Accumulator B Saturation 'Sticky' Status bit(1,4)
1 = Accumulator B is saturated or has been saturated at some time
0 = Accumulator B is not saturated

bit 11 **OAB:** OA || OB Combined Accumulator Overflow Status bit(1)
1 = Accumulators A or B have overflowed
0 = Neither Accumulators A or B have overflowed

bit 10 **SAB:** SA || SB Combined Accumulator 'Sticky' Status bit(1)
1 = Accumulators A or B are saturated or have been saturated at some time
0 = Neither Accumulators A or B are saturated

bit 9 **DA:** DO Loop Active bit(1)
1 = DO loop is in progress
0 = DO loop is not in progress

bit 8 **DC:** MCU ALU Half Carry/$\overline{\text{Borrow}}$ bit
1 = A carry-out from the 4th low-order bit (for byte-sized data) or 8th low-order bit (for word-sized data) of the result occurred
0 = No carry-out from the 4th low-order bit (for byte-sized data) or 8th low-order bit (for word-sized data) of the result occurred

Note 1: This bit is available on dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices only.

2: The IPL<2:0> bits are concatenated with the IPL<3> bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the IPL, if IPL<3> = 1. User interrupts are disabled when IPL<3> = 1.

3: The IPL<2:0> Status bits are read-only when the NSTDIS bit (INTCON1<15>) = 1.

4: A data write to the SR register can modify the SA and SB bits by either a data write to SA and SB or by clearing the SAB bit. To avoid a possible SA or SB bit write race condition, the SA and SB bits should not be modified using bit operations.

REGISTER 11-13: RPINR23: PERIPHERAL PIN SELECT INPUT REGISTER 23

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	SS2R<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as ‘0’

bit 6-0 **SS2R<6:0>:** Assign SPI2 Slave Select ($\overline{SS2}$) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

REGISTER 11-14: RPINR26: PERIPHERAL PIN SELECT INPUT REGISTER 26 (dsPIC33EPXXXGP/MC50X DEVICES ONLY)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	C1RXR<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as ‘0’

bit 6-0 **C1RXR<6:0>:** Assign CAN1 RX Input (CRX1) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

NOTES:

13.0 TIMER2/3 AND TIMER4/5

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Timers"** (DS70362) of the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Timer2/3 and Timer4/5 modules are 32-bit timers, which can also be configured as four independent 16-bit timers with selectable operating modes.

As 32-bit timers, Timer2/3 and Timer4/5 operate in three modes:

- Two Independent 16-Bit Timers (e.g., Timer2 and Timer3) with all 16-Bit Operating modes (except Asynchronous Counter mode)
- Single 32-Bit Timer
- Single 32-Bit Synchronous Counter

They also support these features:

- Timer Gate Operation
- Selectable Prescaler Settings
- Timer Operation during Idle and Sleep modes
- Interrupt on a 32-Bit Period Register Match
- Time Base for Input Capture and Output Compare Modules (Timer2 and Timer3 only)
- ADC1 Event Trigger (32-bit timer pairs, and Timer3 and Timer5 only)

Individually, all four of the 16-bit timers can function as synchronous timers or counters. They also offer the features listed previously, except for the event trigger; this is implemented only with Timer2/3. The operating modes and enabled features are determined by setting the appropriate bit(s) in the T2CON, T3CON, and T4CON, T5CON registers. T2CON and T4CON are shown in generic form in Register 13-1. T3CON and T5CON are shown in Register 13-2.

For 32-bit timer/counter operation, Timer2 and Timer4 are the least significant word (lsw); Timer3 and Timer5 are the most significant word (msw) of the 32-bit timers.

Note: For 32-bit operation, T3CON and T5CON control bits are ignored. Only T2CON and T4CON control bits are used for setup and control. Timer2 and Timer4 clock and gate inputs are utilized for the 32-bit timer modules, but an interrupt is generated with the Timer3 and Timer5 interrupt flags.

A block diagram for an example 32-bit timer pair (Timer2/3 and Timer4/5) is shown in Figure 13-3.

Note: Only Timer2, 3, 4 and 5 can trigger a DMA data transfer.

16.0 HIGH-SPEED PWM MODULE (dsPIC33EPXXXMC20X/50X AND PIC24EPXXXMC20X DEVICES ONLY)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"High-Speed PWM"** (DS70645) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices support a dedicated Pulse-Width Modulation (PWM) module with up to 6 outputs.

The high-speed PWMx module consists of the following major features:

- Three PWM generators
- Two PWM outputs per PWM generator
- Individual period and duty cycle for each PWM pair
- Duty cycle, dead time, phase shift and frequency resolution of TCY/2 (7.14 ns at FCY = 70MHz)
- Independent Fault and current-limit inputs for six PWM outputs
- Redundant output
- Center-Aligned PWM mode
- Output override control
- Chop mode (also known as Gated mode)
- Special Event Trigger
- Prescaler for input clock
- PWMxL and PWMxH output pin swapping
- Independent PWM frequency, duty cycle and phase-shift changes for each PWM generator
- Dead-time compensation
- Enhanced Leading-Edge Blanking (LEB) functionality
- Frequency resolution enhancement
- PWM capture functionality

Note: In Edge-Aligned PWM mode, the duty cycle, dead time, phase shift and frequency resolution are 8.32 ns.

The high-speed PWMx module contains up to three PWM generators. Each PWM generator provides two PWM outputs: PWMxH and PWMxL. The master time base generator provides a synchronous signal as a common time base to synchronize the various PWM outputs. The individual PWM outputs are available on the output pins of the device. The input Fault signals and current-limit signals, when enabled, can monitor and protect the system by placing the PWM outputs into a known "safe" state.

Each PWMx can generate a trigger to the ADC module to sample the analog signal at a specific instance during the PWM period. In addition, the high-speed PWMx module also generates a Special Event Trigger to the ADC module based on either of the two master time bases.

The high-speed PWMx module can synchronize itself with an external signal or can act as a synchronizing source to any external device. The SYNCI1 input pin that utilizes PPS, can synchronize the high-speed PWMx module with an external signal. The SYNCO1 pin is an output pin that provides a synchronous signal to an external device.

Figure 16-1 illustrates an architectural overview of the high-speed PWMx module and its interconnection with the CPU and other peripherals.

16.1 PWM Faults

The PWMx module incorporates multiple external Fault inputs to include FLT1 and FLT2 which are remappable using the PPS feature, FLT3 and FLT4 which are available only on the larger 44-pin and 64-pin packages, and FLT32 which has been implemented with Class B safety features, and is available on a fixed pin on all dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

These Faults provide a safe and reliable way to safely shut down the PWM outputs when the Fault input is asserted.

16.1.1 PWM FAULTS AT RESET

During any Reset event, the PWMx module maintains ownership of the Class B Fault, FLT32. At Reset, this Fault is enabled in Latched mode to ensure the fail-safe power-up of the application. The application software must clear the PWM Fault before enabling the high-speed motor control PWMx module. To clear the Fault condition, the FLT32 pin must first be pulled low externally or the internal pull-down resistor in the CNPDx register can be enabled.

Note: The Fault mode may be changed using the FLTMOD<1:0> bits (FCLCON<1:0>), regardless of the state of FLT32.

21.0 ENHANCED CAN (ECAN™) MODULE (dsPIC33EPXXXGP/MC50X DEVICES ONLY)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Enhanced Controller Area Network (ECAN™)"** (DS70353) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

21.1 Overview

The Enhanced Controller Area Network (ECAN) module is a serial interface, useful for communicating with other CAN modules or microcontroller devices. This interface/protocol was designed to allow communications within noisy environments. The dsPIC33EPXXXGP/MC50X devices contain one ECAN module.

The ECAN module is a communication controller implementing the CAN 2.0 A/B protocol, as defined in the BOSCH CAN specification. The module supports CAN 1.2, CAN 2.0A, CAN 2.0B Passive and CAN 2.0B Active versions of the protocol. The module implementation is a full CAN system. The CAN specification is not covered within this data sheet. The reader can refer to the BOSCH CAN specification for further details.

The ECAN module features are as follows:

- Implementation of the CAN protocol, CAN 1.2, CAN 2.0A and CAN 2.0B
- Standard and extended data frames
- 0-8 bytes data length
- Programmable bit rate up to 1 Mbit/sec
- Automatic response to remote transmission requests
- Up to eight transmit buffers with application specified prioritization and abort capability (each buffer can contain up to 8 bytes of data)
- Up to 32 receive buffers (each buffer can contain up to 8 bytes of data)
- Up to 16 full (Standard/Extended Identifier) acceptance filters
- Three full acceptance filter masks
- DeviceNet™ addressing support
- Programmable wake-up functionality with integrated low-pass filter
- Programmable Loopback mode supports self-test operation
- Signaling via interrupt capabilities for all CAN receiver and transmitter error states
- Programmable clock source
- Programmable link to Input Capture (IC2) module for time-stamping and network synchronization
- Low-power Sleep and Idle mode

The CAN bus module consists of a protocol engine and message buffering/control. The CAN protocol engine handles all functions for receiving and transmitting messages on the CAN bus. Messages are transmitted by first loading the appropriate data registers. Status and errors can be checked by reading the appropriate registers. Any message detected on the CAN bus is checked for errors and then matched against filters to see if it should be received and stored in one of the receive registers.

21.2 Modes of Operation

The ECAN module can operate in one of several operation modes selected by the user. These modes include:

- Initialization mode
- Disable mode
- Normal Operation mode
- Listen Only mode
- Listen All Messages mode
- Loopback mode

Modes are requested by setting the REQOP<2:0> bits (CxCTRL1<10:8>). Entry into a mode is Acknowledged by monitoring the OPMODE<2:0> bits (CxCTRL1<7:5>). The module does not change the mode and the OPMODEx bits until a change in mode is acceptable, generally during bus Idle time, which is defined as at least 11 consecutive recessive bits.

21.3 ECAN Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

21.3.1 KEY RESOURCES

- **"Enhanced Controller Area Network (ECAN™)"** (DS70353) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

REGISTER 21-4: CxFCTRL: ECANx FIFO CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0	U-0
DMABS2	DMABS1	DMABS0	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	FSA4	FSA3	FSA2	FSA1	FSA0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **DMABS<2:0>:** DMA Buffer Size bits
111 = Reserved
110 = 32 buffers in RAM
101 = 24 buffers in RAM
100 = 16 buffers in RAM
011 = 12 buffers in RAM
010 = 8 buffers in RAM
001 = 6 buffers in RAM
000 = 4 buffers in RAM

bit 12-5 **Unimplemented:** Read as ‘0’

bit 4-0 **FSA<4:0>:** FIFO Area Starts with Buffer bits
11111 = Read Buffer RB31
11110 = Read Buffer RB30
•
•
•
00001 = TX/RX Buffer TRB1
00000 = TX/RX Buffer TRB0

BUFFER 21-5: ECAN™ MESSAGE BUFFER WORD 4

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 3							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 2							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Byte 3<15:8>:** ECAN Message Byte 3 bits

bit 7-0 **Byte 2<7:0>:** ECAN Message Byte 2 bits

BUFFER 21-6: ECAN™ MESSAGE BUFFER WORD 5

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 5							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 4							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Byte 5<15:8>:** ECAN Message Byte 5 bits

bit 7-0 **Byte 4<7:0>:** ECAN Message Byte 4 bits

BUFFER 21-7: ECAN™ MESSAGE BUFFER WORD 6

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 7							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 6							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Byte 7<15:8>:** ECAN Message Byte 7 bits

bit 7-0 **Byte 6<7:0>:** ECAN Message Byte 6 bits

BUFFER 21-8: ECAN™ MESSAGE BUFFER WORD 7

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	FILHIT4(1)	FILHIT3(1)	FILHIT2(1)	FILHIT1(1)	FILHIT0(1)
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12-8 **FILHIT<4:0>:** Filter Hit Code bits(1)

Encodes number of filter that resulted in writing this buffer.

bit 7-0 **Unimplemented:** Read as ‘0’

Note 1: Only written by module for receive buffers, unused for transmit buffers.

NOTES:

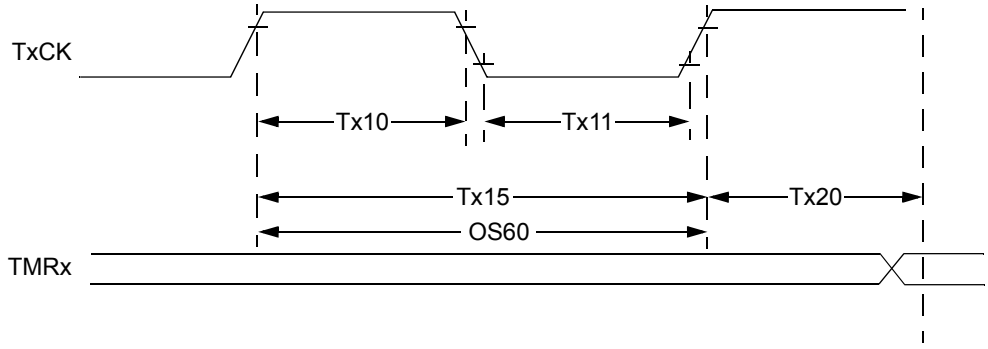
TABLE 30-8: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended		
Parameter No.	**Typ.**	**Max.**	**Units**	**Conditions**	
Power-Down Current (I_{PD})(1) – dsPIC33EP32GP50X, dsPIC33EP32MC20X/50X and PIC24EP32GP/MC20X					
DC60d	30	100	μA	-40°C	3.3V
DC60a	35	100	μA	+25°C	
DC60b	150	200	μA	+85°C	
DC60c	250	500	μA	+125°C	
Power-Down Current (I_{PD})(1) – dsPIC33EP64GP50X, dsPIC33EP64MC20X/50X and PIC24EP64GP/MC20X					
DC60d	25	100	μA	-40°C	3.3V
DC60a	30	100	μA	+25°C	
DC60b	150	350	μA	+85°C	
DC60c	350	800	μA	+125°C	
Power-Down Current (I_{PD})(1) – dsPIC33EP128GP50X, dsPIC33EP128MC20X/50X and PIC24EP128GP/MC20X					
DC60d	30	100	μA	-40°C	3.3V
DC60a	35	100	μA	+25°C	
DC60b	150	350	μA	+85°C	
DC60c	550	1000	μA	+125°C	
Power-Down Current (I_{PD})(1) – dsPIC33EP256GP50X, dsPIC33EP256MC20X/50X and PIC24EP256GP/MC20X					
DC60d	35	100	μA	-40°C	3.3V
DC60a	40	100	μA	+25°C	
DC60b	250	450	μA	+85°C	
DC60c	1000	1200	μA	+125°C	
Power-Down Current (I_{PD})(1) – dsPIC33EP512GP50X, dsPIC33EP512MC20X/50X and PIC24EP512GP/MC20X					
DC60d	40	100	μA	-40°C	3.3V
DC60a	45	100	μA	+25°C	
DC60b	350	800	μA	+85°C	
DC60c	1100	1500	μA	+125°C	

Note 1: I_{PD} (Sleep) current is measured as follows:

- CPU core is off, oscillator is configured in EC mode and external clock is active; OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR}$ = V_{DD}, WDT and FSCM are disabled
- All peripheral modules are disabled (PMDx bits are all set)
- The VREGS bit (RCON<8>) = 0 (i.e., core regulator is set to standby while the device is in Sleep mode)
- The VREGSF bit (RCON<11>) = 0 (i.e., Flash regulator is set to standby while the device is in Sleep mode)
- JTAG is disabled

FIGURE 30-5: TIMER1-TIMER5 EXTERNAL CLOCK TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

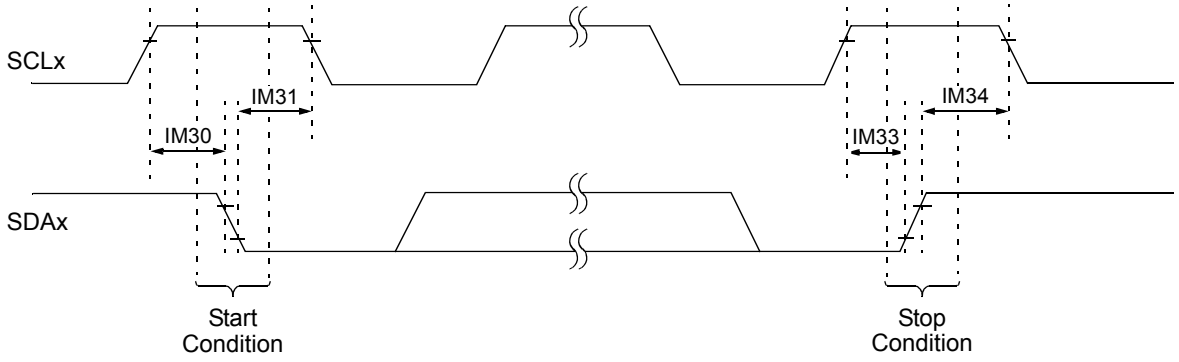
TABLE 30-23: TIMER1 EXTERNAL CLOCK TIMING REQUIREMENTS(1)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(2)**		**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
TA10	TTXH	T1CK High Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TA15, N = prescaler value (1, 8, 64, 256)
			Asynchronous	35	—	—	ns	
TA11	TTXL	T1CK Low Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TA15, N = prescaler value (1, 8, 64, 256)
			Asynchronous	10	—	—	ns	
TA15	TTXP	T1CK Input Period	Synchronous mode	Greater of: 40 or (2 TCY + 40)/N	—	—	ns	N = prescale value (1, 8, 64, 256)
OS60	Ft1	T1CK Oscillator Input Frequency Range (oscillator enabled by setting bit, TCS (T1CON<1>))		DC	—	50	kHz	
TA20	TCKEXTMRL	Delay from External T1CK Clock Edge to Timer Increment		0.75 TCY + 40	—	1.75 TCY + 40	ns	

Note 1: Timer1 is a Type A.

2: These parameters are characterized, but are not tested in manufacturing.

FIGURE 30-30: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (MASTER MODE)



Note: Refer to Figure 30-1 for load conditions.

FIGURE 30-31: I2Cx BUS DATA TIMING CHARACTERISTICS (MASTER MODE)

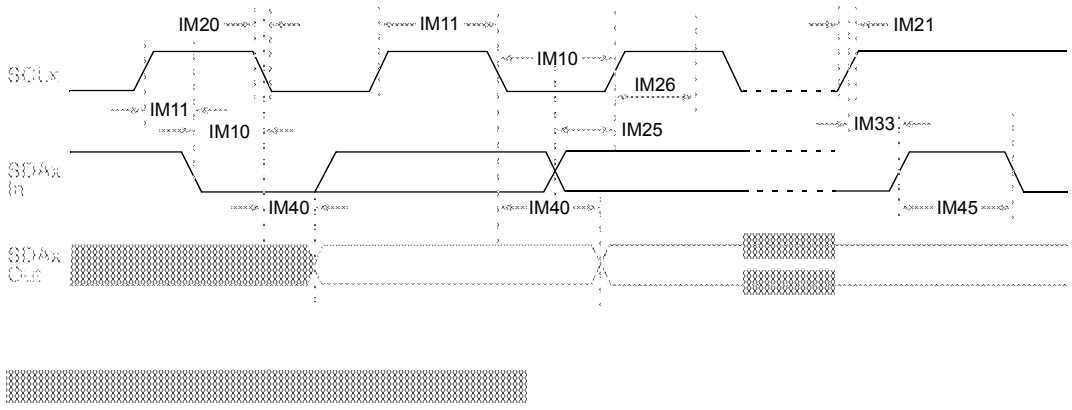


TABLE 30-54: OP AMP/COMPARATOR VOLTAGE REFERENCE SETTLING TIME SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions (see Note 2): 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
VR310	TSET	Settling Time	—	1	10	μs	**(Note 1)**

Note 1: Settling time is measured while CVRR = 1 and CVR<3:0> bits transition from '0000' to '1111'.

2: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

TABLE 30-55: OP AMP/COMPARATOR VOLTAGE REFERENCE SPECIFICATIONS

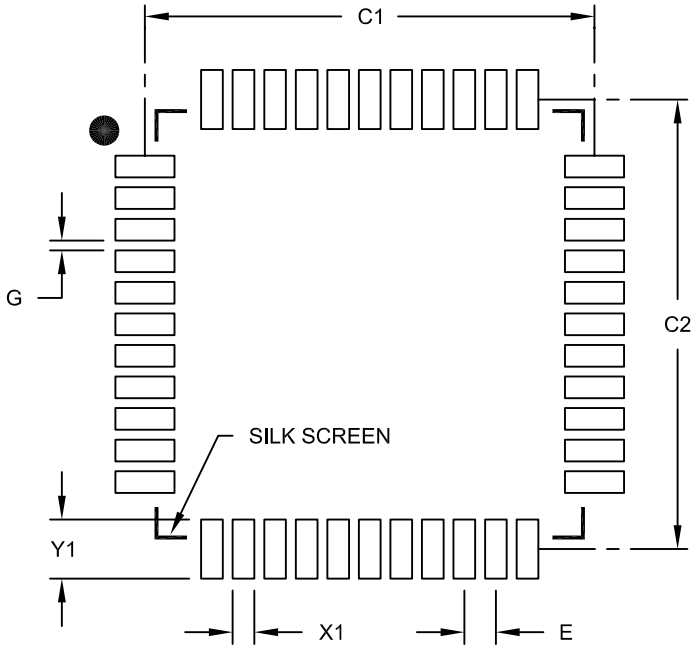
DC CHARACTERISTICS			Standard Operating Conditions (see Note 1): 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
VRD310	CVRES	Resolution	CVRSRC/24	—	CVRSRC/32	LSb	
VRD311	CVRAA	Absolute Accuracy(2)	—	±25	—	mV	CVRSRC = 3.3V
VRD313	CVRSRC	Input Reference Voltage	0	—	AVDD + 0.3	V	
VRD314	CVROUT	Buffer Output Resistance(2)	—	1.5k	—	Ω	

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: Parameter is characterized but not tested in manufacturing.

44-Lead Plastic Thin Quad Flatpack (PT) 10X10X1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.80 BSC		
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X44)	X1			0.55
Contact Pad Length (X44)	Y1			1.50
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2076B

TABLE A-5: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 30.0 "Electrical Characteristics"	• Throughout: qualifies all footnotes relating to the operation of analog modules below VDDMIN (replaces "will have" with "may have") • Throughout: changes all references of SPI timing parameter symbol "TscP" to "FscP" • Table 30-1: changes VDD range to 3.0V to 3.6V • Table 30-4: removes Parameter DC12 (RAM Retention Voltage) • Table 30-7: updates Maximum values at 10 and 20 MIPS • Table 30-8: adds Maximum IPD values, and removes all ΔIWDT entries • Adds new Table 30-9 (Watchdog Timer Delta Current) with consolidated values removed from Table 30-8. All subsequent tables are renumbered accordingly. • Table 30-10: adds footnote for all parameters for 1:2 Doze ratio • Table 30-11: - changes Minimum and Maximum values for D120 and D130 - adds Minimum and Maximum values for D131 - adds Minimum and Maximum values for D150 through D156, and removes Typical values • Table 30-12: - reformats table for readability - changes IOL conditions for DO10 • Table 30-14: adds footnote to D135 • Table 30-17: changes Minimum and Maximum values for OS30 • Table 30-19: - splits temperature range and adds new values for F20a - reduces temperature range for F20b to extended temperatures only • Table 30-20: - splits temperature range and adds new values for F21a - reduces temperature range for F20b to extended temperatures only • Table 30-53: - adds Maximum value to CM30 - adds footnote ("Parameter characterized...") to multiple parameters • Table 30-55: adds Minimum and Maximum values for all CTMUI specifications, and removes Typical values • Table 30-57: adds new footnote to AD09 • Table 30-58: - removes all specifications for accuracy with external voltage references - removes Typical values for AD23a and AD24a - replaces Minimum and Maximum values for AD21a, AD22a, AD23a and AD24a with new values, split by Industrial and Extended temperatures - removes Maximum value of AD30 - removes Minimum values from AD31a and AD32a - adds or changes Typical values for AD30, AD31a, AD32a and AD33a • Table 30-59: - removes all specifications for accuracy with external voltage references - removes Maximum value of AD30 - removes Typical values for AD23b and AD24b - replaces Minimum and Maximum values for AD21b, AD22b, AD23b and AD24b with new values, split by Industrial and Extended temperatures - removes Minimum and Maximum values from AD31b, AD32b, AD33b and AD34b - adds or changes Typical values for AD30, AD31a, AD32a and AD33a • Table 30-61: Adds footnote to AD51
Section 32.0 "DC and AC Device Characteristics Graphs"	• Updates Figure 32-6 (Typical IDD @ 3.3V) with individual current vs. processor speed curves for the different program memory sizes
Section 33.0 "Packaging Information"	• Replaces drawing C04-149C (64-pin QFN, 7.15 x 7.15 exposed pad) with C04-154A (64-pin QFN, 5.4 x 5.4 exposed pad)